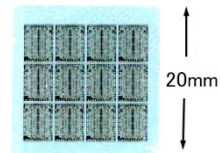
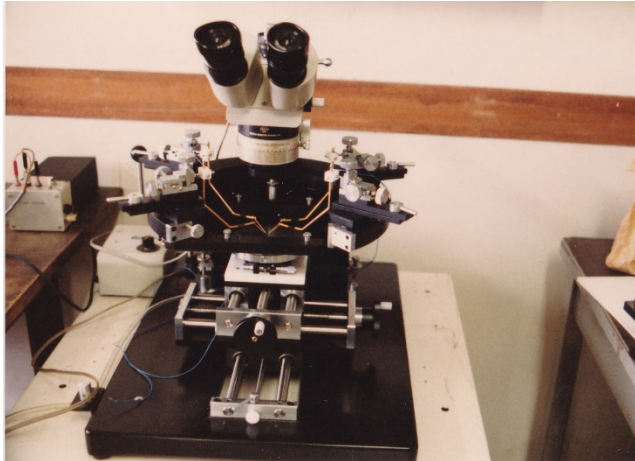


12 Assembly & measurement



CMOS IC fabricated on a 20mm square wafer



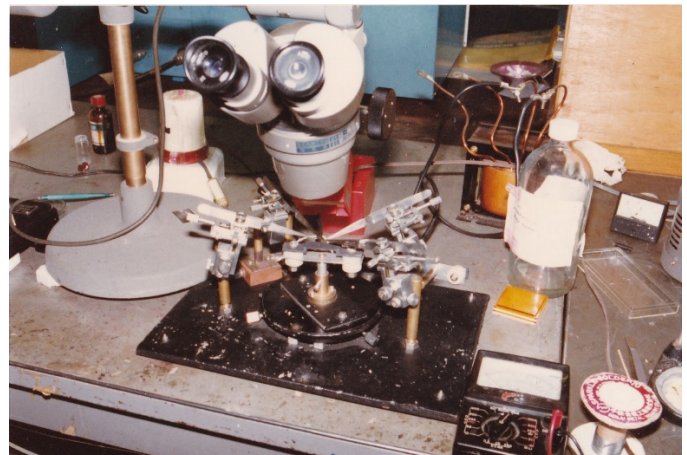
Wafer prober



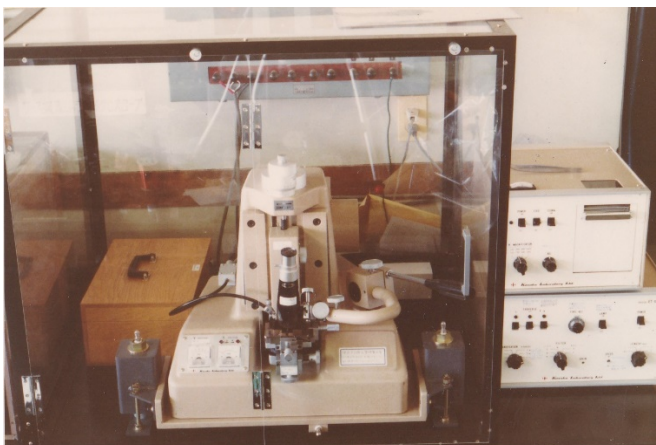
Dicer



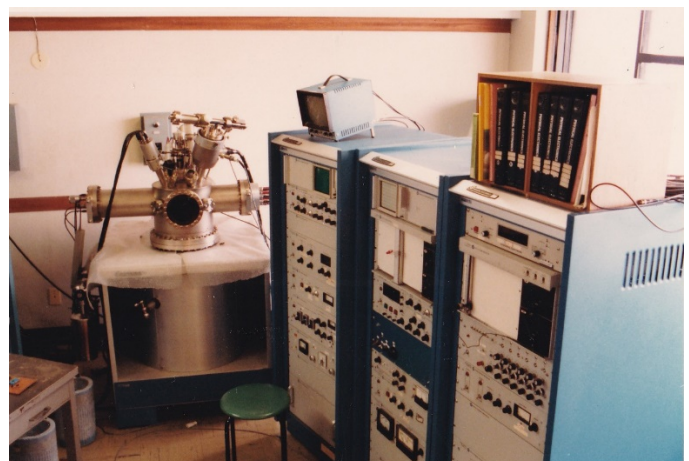
Ultrasonic wire bonder (displayed)



Micro soldering (and connection by conductive paste)



Surface profile meter



Auger electron spectrometer